

**Average Weight: 3.7666 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.083040</b>	<b>2.20</b>
	Silicon	7440-21-3	100.00		0.083040	
<b>Die Attach Material</b>					<b>0.012939</b>	<b>0.34</b>
	Polymetric material	Proprietary	3.00		0.000388	
	Di-Ester Resin	Proprietary	7.50		0.000970	
	Functionalized Ester	Proprietary	3.00		0.000388	
	Silver	7440-22-4	86.50		0.011192	
<b>Mold Compound</b>					<b>1.791220</b>	<b>47.56</b>
	Solid Epoxy Resin	Trade Secret	5.00		0.089561	
	Phenol Resin	Trade Secret	5.00		0.089561	
	Fused Silica	60676-86-0	83.00		1.486711	
	Metal Hydro Oxide	Trade Secret	1.00		0.017912	
	Carbon Black	1333-86-4	1.00		0.017912	
	Crystalline Silica	14808-60-7	5.00		0.089561	
<b>Gold Wire</b>					<b>0.019700</b>	<b>0.52</b>
	Gold	7440-57-5	99.05		0.195120	
	Palladium	7440-05-3	0.95		0.000187	
<b>Solder Balls</b>					<b>0.976180</b>	<b>25.92</b>
	Tin (Sn)	7440-31-5	95.50		0.932252	
	Silver (Ag)	7440-22-4	4.00		0.039047	
	Copper (Cu)	7440-50-8	0.50		0.004881	
<b>Heat Spreader</b>					<b>0.883503</b>	<b>23.46</b>
	Copper (Cu)	7440-50-8	46.27	Metal Layer	0.408797	
	Nickel	7440-02-0	0.60	Metal Layer	0.005301	
	Gold	7440-57-5	0.13	Metal Layer	0.001149	
	Glass Fiber (GF)	N/A	23.00		0.203206	
	Flame Retardant	N/A	3.20		0.028272	
	BT (core)	N/A	16.80		0.148429	
	Solder Mask	N/A	10.00		0.148429	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/26/06	1.0	Initial Xilinx release.
01/16/12	1.1	CAS# Update.

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